INTEGRATED CIRCUITS

DATA SHEET

· Com. Cn

74ABT161543 74ABTH161543

16-bit latched transceiver with dual enable and master reset (3-State)

Product specification Supersedes data of 1995 Sep 18 IC23 Data Handbook 1998 Feb 27





16-bit latched transceiver with dual enable and master reset (3-State)

74ABT161543 74ABTH161543

FEATURES

- Two 8-bit octal transceivers with D-type latch
- Live insertion/extraction permitted
- Power-up 3-State
- Power-up reset
- Multiple V_{CC} and GND pins minimize switching noise
- Back-to-back registers for storage
- Separate controls for data flow in each direction
- 74ABTH161543 incorporates Bus hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model
- Same function as ABT16543 except for additional Master Reset control pins

DESCRIPTION

The 74ABT161543 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high

The 74ABT161543 16-bit registered transceiver contains two sets of D-type latches for temporary storage of data flowing in either direction. Separate Latch Enable (nLEAB, nLEBA) and Output Enable (nOEAB, nOEBA) inputs are provided for each register to permit independent control of data transfer in either direction. Master reset (MR) clears all registers simultaneously and sets them Low. The outputs are guaranteed to sink 64mA.

Two options are available, 74ABT161543 which does not have the Bus hold feature and 74ABTH161543 which inorporates the Bus hold feature.

QUICK REFERENCE DATA

control pins	as AB i 16543 except for additional Mas	ter Reset		
QUICK REFE	ERENCE DATA	3. 34		
SYMBOL	PARAMETER	CONDITIONS $T_{amb} = 25^{\circ}C; GND = 0V$	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nBx	$C_L = 50pF; V_{CC} = 5V$	2.5 2.2	ns
C _{IN}	Input capacitance	$V_I = 0V \text{ or } V_{CC}$	3	pF
C _{I/O}	I/O capacitance	V _O = 0V or V _{CC} ; 3-State	7	pF
I _{CCZ}	Quiescent supply current	Outputs disabled; V _{CC} = 5.5V	500	μΑ
Iccl	Quiescent supply current	Outputs low; V _{CC} = 5.5V	9	mA

ORDERING INFORMATION

PACKAGES		TEMPERATURE RANGE	ORDER CODE	DRAWING NUMBER
56-pin plastic SSOP Type III		-40°C to +85°C	BT161543DL	SOT371-1
56-pin plastic TSSOP Type II	\Box	-40°C to +85°C	BT161543DGG	SOT364-1

ORDERING INFORMATION

ONDERNING IN ORMATION				
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	-40°C to +85°C	74ABT161543 DL	BT161543 DL	SOT371-1
56-Pin Plastic TSSOP Type II	-40°C to +85°C	74ABT161543 DGG	BT161543 DGG	SOT364-1
56-Pin Plastic SSOP Type III	-40°C to +85°C	74ABTH161543 DL	BH161543 DL	SOT371-1
56-Pin Plastic TSSOP Type II	-40°C to +85°C	74ABTH161543 DGG	BH161543 DGG	SOT364-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
5, 6, 8, 9, 10, 12, 13, 14 15, 16, 17, 19, 20, 21, 23, 24	1A0 – 1A7, 2A0 – 2A7	Data inputs/outputs
52, 51, 49, 48, 47, 45, 44, 43 42, 41, 40,38, 37, 36, 34, 33	1B0 – 1B7, 2B0 – 2B7	Data inputs/outputs
1, 56 28, 29	1 <u>OEAB</u> , 1 <u>OEBA,</u> 2OEAB, 2OEBA	A to B / B to A Output Enable inputs (active-Low)
3, 54 26, 31	1 <u>EAB</u> , 1 <u>EBA,</u> 2EAB, 2EBA	A to B / B to A Enable inputs (active-Low)
2, 55 27, 30	1 <u>LEAB</u> , 1 <u>LEBA,</u> 2 <u>LEAB</u> , 2 <u>LEBA</u>	A to B / B to A Latch Enable inputs (active-Low)
4, 25	MRab, MRba	Master reset
11, 18, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	V _{CC}	Positive supply voltage

16-bit latched transceiver with dual enable and master reset (3-State)

74ABT161543 74ABTH161543

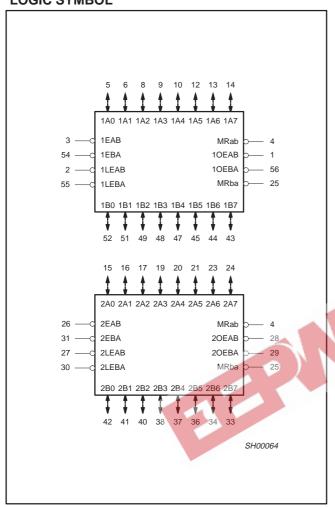
LOGIC SYMBOL (IEEE/IEC) **PIN CONFIGURATION** 1OEBA 1OEAB 56 R6/R12 MRab 1LEAB 2 55 1LEBA 2EN4 1OEAB 1EAB 3 54 1EBA 1EAB G2 MRab 53 GND 4 2C6 1LEAB 5 1A0 52 1B0 2OEAB 8EN10 51 1B1 1A1 6 26 2EAB 50 7 VCC 27 2LEAB 8C12 8 49 25 R5/R11 MRba 9 48 1B3 1A3 56 1OEBA 1EN3 1A4 10 47 1B4 G1 1EBA 12 45 1B5 55 1A5 1LEBA 1C5 44 1B6 7EN9 2OEBA 43 1B7 2EBA G7 42 2B0 30 2LEBA 7C11 41 2B1 40 2B2 1A0 ∇3 5D 1B0 6D GND 39 GND 6 19 38 2B3 1B1 1A1 20 37 1B2 1A2 2A4 2B4 1A3 1B3 21 36 2B5 1A4 22 35 VCC VCC 1B5 1A5 2A6 23 34 2B6 13 1B6 2A7 24 33 14 1A7 32 25 GND MRba 15 42 ∇9 2B0 2A0 11D 2EAB 26 31 2EBA 12D 2LEAB 27 30 2LEBA _16 2B1 2OEAB 29 2OEBA 40 SH00061 2B3 2A3 2B4 2A5 2B5 2A6 2B6 2B7 2A7

SH00060

16-bit latched transceiver with dual enable and master reset (3-State)

74ABT161543 74ABTH161543

LOGIC SYMBOL



FUNCTIONAL DESCRIPTION

The 74ABT161543 contains two sets of eight D-type latches, with separate control pins for each set. Using data flow from A to B as an example, when the A-to-B Enable (nEAB) input and the A-to-B Latch Enable (nEAB) input are Low the A-to-B path is transparent.

A subsequent Low-to-High transition of the nLEAB signal puts the A data into the latches where it is stored and the B outputs no longer change with the A inputs. With EAB and nOEAB both Low, the 3-State B output buffers are active and display the data present at the outputs of the A latches.

Control of data flow from B to A is similar, but using the n $\overline{\text{EBA}}$, n $\overline{\text{LEBA}}$, and n $\overline{\text{OEBA}}$ inputs.



FUNCTION TABLE

		INPUTS		OUTPUTS	STATUS	
nOEXX	nMRXX	nEXX	nLEXX	nAx or nBx	nBx or nAx	SIATOS
L	L	L	Х	X	L	Clear
Н	Х	Х	Х	Х	Z	Disabled
Х	Х	Н	Х	Х	Z	Disabled
L L	H H	↑	L L	h I	Z Z	Disabled + Latch
L L	H H	L L	<u>†</u>	h I	H	Latch + Display
L L	H H	L L	L L	H L	H L	Transparent
L	Н	L	Н	Х	NC	Hold

H = High voltage level

h = High voltage level one set-up time prior to the Low-to-High transition of nEXX or nEXX (XX = AB or BA)

L = Low voltage level

Let $\overline{\mathsf{Low}}$ voltage level one set-up time prior to the Low-to-High transition of $\overline{\mathsf{nLEXX}}$ or $\overline{\mathsf{nEXX}}$ (XX = AB or BA)

X = Don't care

= Low-to-High transition of $n\overline{LEXX}$ or $n\overline{EXX}$ (XX = AB or BA)

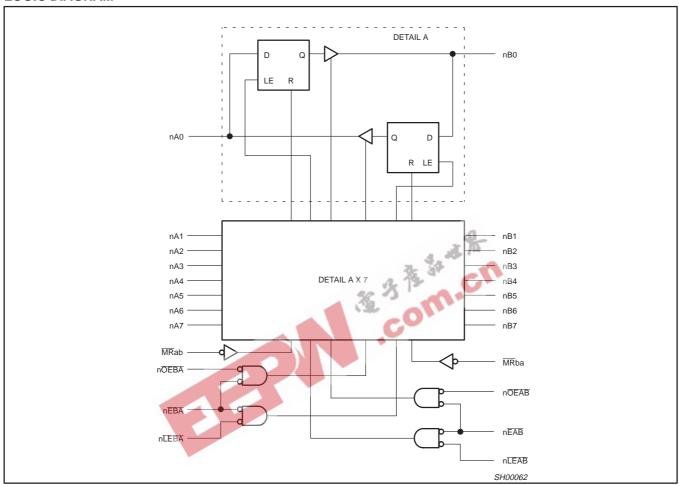
NC= No change

Z = High impedance or "off" state

16-bit latched transceiver with dual enable and master reset (3-State)

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LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	PARAMETER CONDITIONS		UNIT
V _{CC}	DC supply voltage		−0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	– 50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
	DC submit surrent	output in Low state	128	mA
lout	DC output current	output in High state	-64	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

- 1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

16-bit latched transceiver with dual enable and master reset (3-State)

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
		Min	Max	
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Low-level Input voltage		0.8	V
I _{OH}	High-level output current		-32	mA
I _{OL}	Low-level output current		64	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	+85	°C	

DC ELECTRICAL CHARACTERISTICS

				LIMITS							
SYMBOL	PARAMETER	TEST CONDITIONS	TEST CONDITIONS		TEST CONDITIONS T _{amb} = +25°C				T _{amb} =	-40°C 85°C	UNIT
			- X	MIN	TYP	MAX	MIN	MAX	1		
V _{IK}	Input clamp voltage	V _{CC} = 4.5V; I _{IK} = -18mA	3	A .		-1.2		-1.2	V		
		$V_{CC} = 4.5V$; $I_{OH} = -3mA$; $V_{I} = V_{IL}$ or	r V _{IH}	2.5	3.0		2.5		V		
V _{OH}	High-level output voltage	$V_{CC} = 5.0V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or	r V _{IH}	3.0	3.6		3.0		V		
		$V_{CC} = 4.5 \text{ V}; I_{OH} = -32 \text{mA}; V_{I} = V_{IL}$		2.0	2.7		2.0		V		
V _{OL}	Low-level output voltage	$V_{CC} = 4.5V$; $I_{OL} = 64mA$; $V_I = V_{IL}$ or	V _{IH}		0.36	0.55		0.55	V		
V _{RST}	Power-up output voltage ³	$V_{CC} = 5.5V; I_{O} = 1mA; V_{I} = GND \text{ or }$	V_{CC}		0.13	0.55		0.55	V		
I ₁	Input leakage current	$V_{CC} = 5.5V$; $V_{I} = GND \text{ or } 5.5V$	Control pins		± 0.01	±1.0		±1.0	μΑ		
	Doe Hald company A and B	$V_{CC} = 4.5V; V_I = 0.8V$		35			35				
I _{HOLD}	Bus Hold current A or B Ports ⁵ 74ABTH161543	$V_{CC} = 4.5V; V_I = 2.0V$		-75			-75		μΑ		
		$V_{CC} = 5.5V; V_I = 0 \text{ to } 5.5V$		±800							
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0V; V_{O} \text{ or } V_{I} \le 4.5V$			±1.0	±100		±100	μΑ		
I _{PU/PD}	Power-up/down 3-State output current ⁴	V_{CC} = 2.1V; V_{O} = 0.0V or V_{CC} ; V_{I} = GND or V_{CC} ; V_{OE} = Don't care			±1.0	±50		±50	μА		
I _{IH} + I _{OZH}	3-State output High current	$V_{CC} = 5.5V; V_O = 5.5V; V_I = V_{IL} \text{ or } V_{CC} = 5.5V$	/ _{IH}		1.0	50		50	μΑ		
I _{IL} + I _{OZL}	3-State output Low current	$V_{CC} = 5.5V; V_{O} = 0.0V; V_{I} = V_{IL} \text{ or } V_{I} = V_{IL}$	/ _{IH}		-1.0	-50		-50	μΑ		
I _{CEX}	Output High leakage current	$V_{CC} = 5.5V$; $V_{O} = 5.5V$; $V_{I} = GND$ o	r V _{CC}		1.0	50		50	μΑ		
I _O	Output current ¹	$V_{CC} = 5.5V; V_{O} = 2.5V$		-50	-100	-200	-50	-200	mA		
I _{CCH}		$V_{CC} = 5.5V$; Outputs High, $V_I = GNI$			0.50	1.5		1.5	mA		
I _{CCL}	Quiescent supply current	V_{CC} = 5.5V; Outputs Low, V_I = GND or V_{CC}			9	19		19	mA		
I _{CCZ}	, , , , , , , , , , , , , , , , , , , ,	V_{CC} = 5.5V; Outputs 3–State; V_I = GND or V_{CC}			0.50	1.5		1.5	mA		
Δl _{CC}	Additional supply current per input pin ² 74ABT161543	V_{CC} = 5.5V; one input at 3.4V, other inputs at V_{CC} or GND			5.0	100		100	μА		
Δl _{CC}	Additional supply current per input pin ² 74ABTH161543	V _{CC} = 5.5V; one input at 3.4V, other inputs at V _{CC} or GND			0.20	1		1	mA		

- 1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- 2. This is the increase in supply current for each input at 3.4V.
- For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.
 This parameter is valid for any V_{CC} between 0V and 2.1V, with a transition time of up to 10msec. From V_{CC} = 2.1V to V_{CC} = 5V ± 10% a transition time of up to 100μsec is permitted.

5. This is the bus hold overdrive current required to force the input to the opposite logic state.

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16-bit latched transceiver with dual enable and master reset (3-State)

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AC CHARACTERISTICS

 $\mbox{GND} = \mbox{OV}, \, t_R = t_F = 2.5 \mbox{ns}, \, C_L = 50 \mbox{pF}, \, R_L = 500 \Omega$

					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	7	_{amb} = +25° V _{CC} = +5.0\	C /	T _{amb} = -4 V _{CC} = +5	0 to +85°C .0V ±0.5V	UNIT
			MIN	TYP	MAX	MIN	MAX	1
t _{PLH} t _{PHL}	Propagation delay nAx to nBx, nBx to nAx	2	1.2 1.0	2.5 2.2	3.4 2.9	1.2 1.0	3.9 3.5	ns
t _{PLH} t _{PHL}	Propagation delay LEBA to nAx, LEAB to nBx	1 2	1.2 1.2	3.0 2.6	4.1 3.5	1.2 1.2	5.1 4.1	ns
t _{PHL}	MRba to nAx, MRab to nBx	6	1.2	2.6	3.4	1.2	4.2	ns
t _{PZH} t _{PZL}	Output enable time OEBA to nAx, OEAB to nBx	4 5	1.4 1.4	3.3 3.4	4.4 4.4	1.4 1.4	5.5 5.6	ns
t _{PHZ} t _{PLZ}	Output disable time OEBA to nAx, OEAB to nBx	4 5	1.4 1.4	3.5 2.7	4.8 3.5	1.4 1.4	5.4 4.0	ns
t _{PZH}	Output enable time EBA to nAx, EAB to nBx	4 5	1.4 1.4	3.4 3.5	4.4 4.4	1.4 1.4	5.6 5.7	ns
t _{PHZ} t _{PLZ}	Output disable time EBA to nAx, EAB to nBx	4 5	1.3 1.3	3.5 2.7	4.4 3.5	1.3 1.3	5.4 4.0	ns

AC SETUP REQUIREMENTS

GND = 0V, t_R = t_F = 2.5ns, C_L = 50pF, R_L = 500 Ω

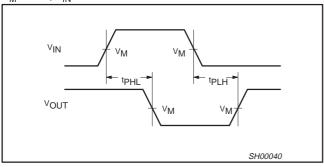
				LIN	NITS	
SYMBOL	PARAMETER	WAVEFORM	T _{amb} = +25°C V _{CC} = +5.0V		T_{amb} = -40 to +85°C V _{CC} = +5.0V ±0.5V	UNIT
			MIN	TYP	MIN	
t _s (H) t _s (L)	Setup time nAx to LEAB, nBx to LEBA	3	1.5 2.0	-0.3 0.1	1.5 2.0	ns
t _h (H) t _h (L)	Hold time nAx to LEAB, nBx to LEBA	3	1.5 2.0	-0.1 0.1	1.5 2.0	ns
t _s (H) t _s (L)	Setup time nAx to EAB, nBx to EBA	3	1.5 2.0	-0.1 0.2	1.5 2.0	ns
t _h (H) t _h (L)	Hold time nAx to EAB, nBx to EBA	3	1.5 2.0	-0.1 -0.1	1.5 2.0	ns
t _w (L)	Latch enable pulse width, Low	3	4.0	2.0	4.0	ns
t _w (L)	MR Pulse width, Low	6	3.0	1.0	3.0	ns

16-bit latched transceiver with dual enable and master reset (3-State)

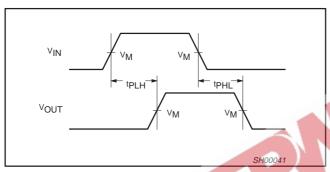
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AC WAVEFORMS

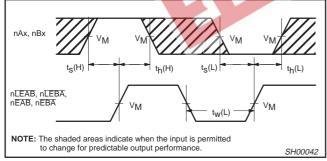
 $V_M = 1.5V$, $V_{IN} = GND$ to 3.0V



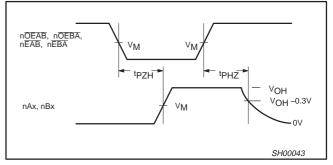
Waveform 1. Propagation Delay For Inverting Output



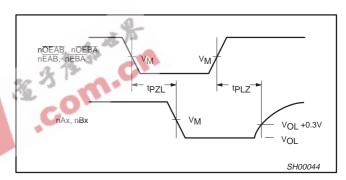
Waveform 2. Propagation Delay For Non-Inverting Output



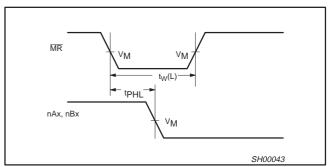
Waveform 3. Data Setup and Hold Times and Latch Enable Pulse Width



Waveform 4. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 5. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

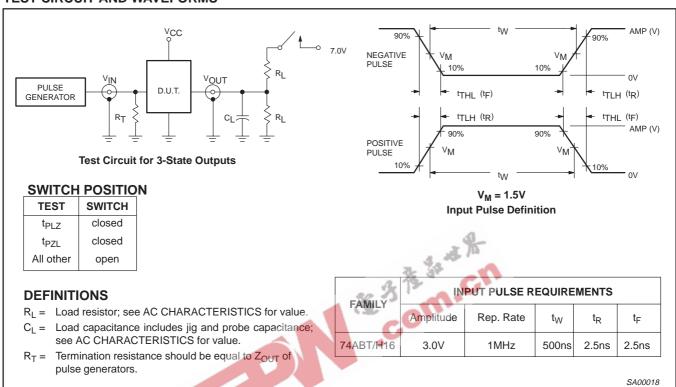


Waveform 6. Master Reset Pulse Width, Master Reset to Output Delay

16-bit latched transceiver with dual enable and master reset (3-State)

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TEST CIRCUIT AND WAVEFORMS

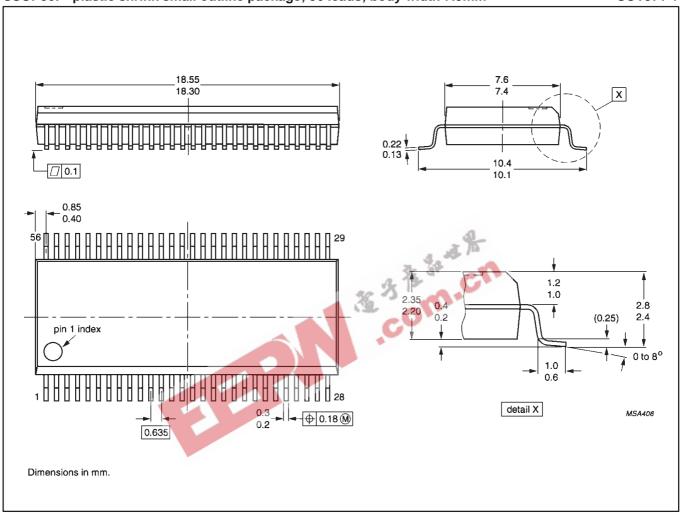


16-bit latched transceiver with dual enable and master reset (3-State)

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SSOP56: plastic shrink small outline package; 56 leads; body width 7.5mm

SOT371-1

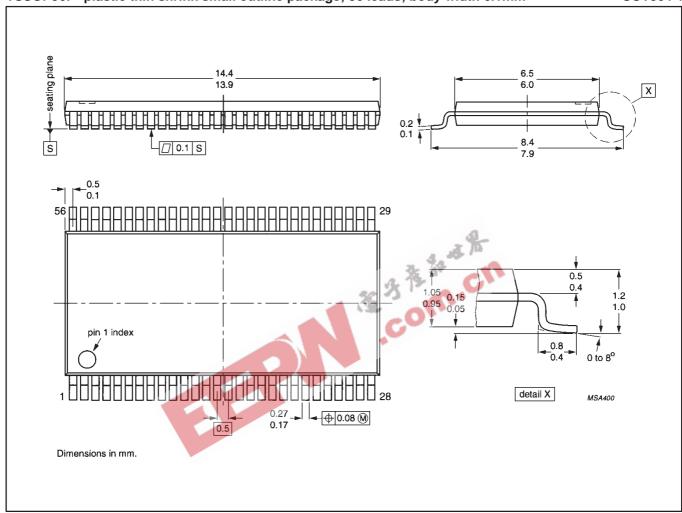


16-bit latched transceiver with dual enable and master reset (3-State)

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TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1mm

SOT364-1



16-bit latched transceiver with dual enable and master reset (3-State)

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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